**Product data sheet** 

# 1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a SOT78 (TO-220AB) plastic package intended for use in applications requiring high bidirectional blocking voltage capability, high current inrush capability and high thermal cycling performance.

### 2. Features and benefits

- High junction operating temperature capability (T<sub>i(max)</sub> = 150 °C)
- · High thermal cycling performance
- · Planar passivated for voltage ruggedness and reliability
- High voltage capacity
- Very high current surge capability

# 3. Applications

- DC Motor control
- Power converter
- · Lighting and temperature control
- · Softstart AC motor control
- AC power control
- Solid State Relay (SSR)

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
Absolute r	maximum rating			,
$V_{RRM}$	repetitive peak reverse voltage		1200	V
I <sub>T(RMS)</sub>	RMS on-state current	half sine wave; $T_{mb} \le 128 ^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3	31	А
I <sub>TSM</sub>	non-repetitive peak on- state current	half sine wave; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 10 \text{ ms}$ ; Fig. 4; Fig. 5	250	А
		half sine wave; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 8.3 \text{ ms}$	275	А
T <sub>j</sub>	junction temperature		150	°C

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7$	-	-	35	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	60	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 20 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.15	1.5	V
Dynamic	characteristics					
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 804 V; $T_j$ = 150 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform;	1000	-	-	V/µs

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	mb	A → K
2	Α	anode	<b>├</b>	G sym037
3	G	gate		Symoon
mb	A	mounting base; connected to anode	<u> </u>	

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package		
	Name	Description	Version
BT152-1200T	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

# 7. Marking

### **Table 4. Marking codes**

Type number	Marking codes
BT152-1200T	BT152-1200T

# 8. Limiting values

### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{DRM}$	repetitive peak off-state voltage		1200	V
$V_{RRM}$	repetitive peak reverse voltage		1200	V
I <sub>T(AV)</sub>	average on-state current	half sine wave; T <sub>mb</sub> ≤ 128 °C;	20	А
I <sub>T(RMS)</sub>	RMS on-state current	half sine wave; T <sub>mb</sub> ≤ 128 °C; Fig. 1; Fig. 2; Fig. 3	31	А
I <sub>TSM</sub>	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 10 ms; Fig. 4; Fig. 5	250	A
		half sine wave; $T_{j(init)} = 25  ^{\circ}C$ ; $t_p = 8.3  ms$	275	A
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t <sub>p</sub> = 10ms; sine wave	312.5	A <sup>2</sup> s
dl <sub>⊤</sub> /dt	rate of rise of on-state current	I <sub>G</sub> = 60mA	150	A/µs
I <sub>GM</sub>	peak gate current		5	А
$V_{GM}$	peak gate voltage		5	V
$P_{GM}$	peak gate power		20	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T <sub>stg</sub>	storage temperature		-40 to 150	°C
T <sub>j</sub>	junction temperature		150	°C

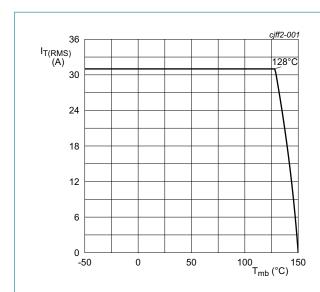
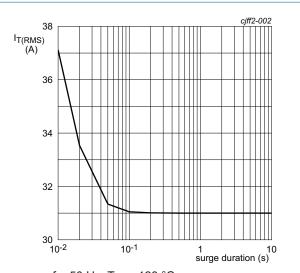


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz;  $T_{mb}$  = 128 °C Fig. 2. RMS on-state current as a function of surge duration; maximum values

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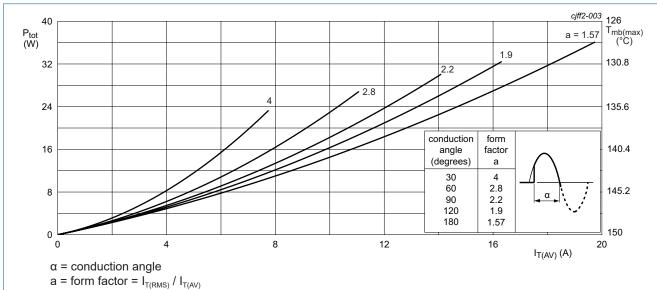


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

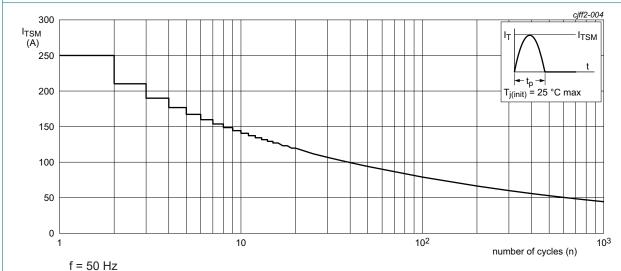
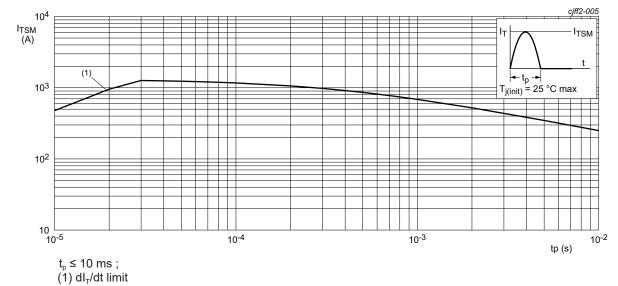


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



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# 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 6	-	-	0.6	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

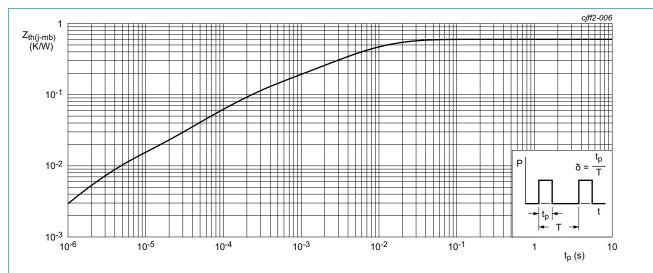


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

# 10. Characteristics

**Table 7. Characteristics** 

10010 11 011	aracteristics		 			
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7$	-	-	35	mA
IL	latching current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 8$	-	-	80	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	60	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 20 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.15	1.5	V
$V_{\text{GT}}$	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$ Fig. 11	-	0.7	1	V
		$V_D = 1200 \text{ V}; I_T = 0.1 \text{ A}; T_j = 150 \text{ °C};$ Fig. 11	0.25	0.4	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 1200 V; T <sub>j</sub> = 150 °C	-	-	2	mA
I <sub>R</sub>	reverse current	V <sub>D</sub> = 1200 V; T <sub>j</sub> = 150 °C	-	-	2	mA
Dynamic c	haracteristics				•	
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 804 V; $T_j$ = 150 °C; $(V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform	1000	-	-	V/µs
$t_{gt}$	gate-controlled turn-on time	$I_{TM} = 20 \text{ A}; V_D = 800 \text{ V}; I_G = 100 \text{ mA};$ $(dI_G/dt)_M = 5 \text{ A}/\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		2	-	μs
t <sub>q</sub>	commutated turn-off time	$V_{DM}$ = 804 V; $T_j$ = 125 °C; $I_{TM}$ = 20 A; $V_R$ = 25 V; $dV_D/dt$ = 50 V/ $\mu$ s; $(dI_T/dt)_M$ = 30 A/ $\mu$ s; $(V_{DM}$ = 67% of $V_{DRM}$ )		70	-	μs

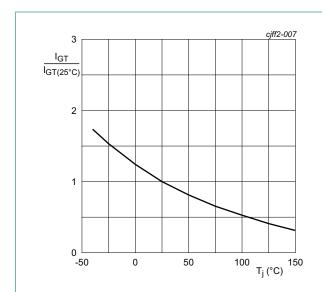


Fig. 7. Normalized gate trigger current as a function of junction temperature

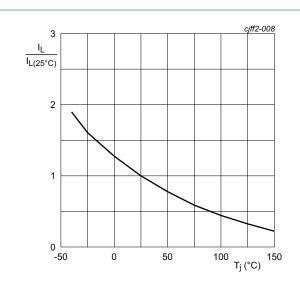


Fig. 8. Normalized latching current as a function of junction temperature

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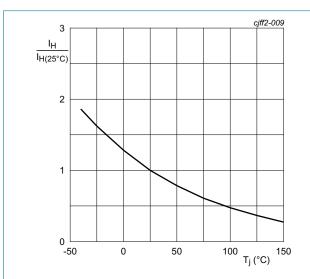
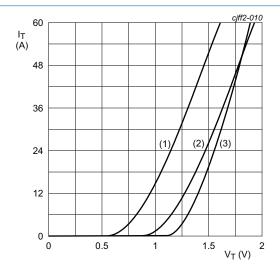


Fig. 9. Normalized holding current as a function of junction temperature



 $V_o$  = 1.067 V;  $R_s$  = 0.0156 Ω (1)  $T_j$  = 150 °C; typical values (2)  $T_j$  = 150 °C; maximum values (3)  $T_j$  = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

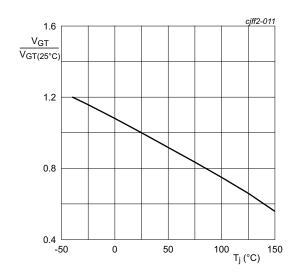
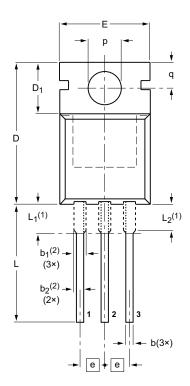


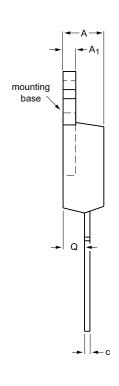
Fig. 11. Normalized gate trigger voltage as a function of junction temperature

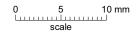
**SOT78** 

# 11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB







### **DIMENSIONS** (mm are the original dimensions)

UNIT	Α	A <sub>1</sub>	b	b <sub>1</sub> <sup>(2)</sup>	b <sub>2</sub> (2)	С	D	D <sub>1</sub>	E	е	L	L <sub>1</sub> (1)	L <sub>2</sub> <sup>(1)</sup> max.	р	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

#### Notes

- 1. Lead shoulder designs may vary.
- 2. Dimension includes excess dambar.

OUTLINE	OUTLINE REFERENCES		EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT78		3-lead TO-220AB	SC-46		<del>08-04-23</del> 08-06-13

SCF

# 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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